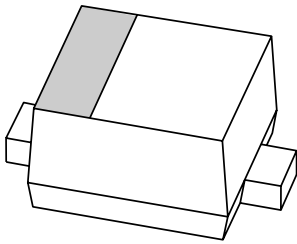


DATA SHEET



1PS79SB31 Schottky barrier diode

Product data sheet

2002 Jan 11

Schottky barrier diode

1PS79SB31

FEATURES

- Very low forward voltage
- Guard ring protected
- Ultra small SMD package.

APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Low current rectification
- Low power consumption applications (e.g. hand-held devices).

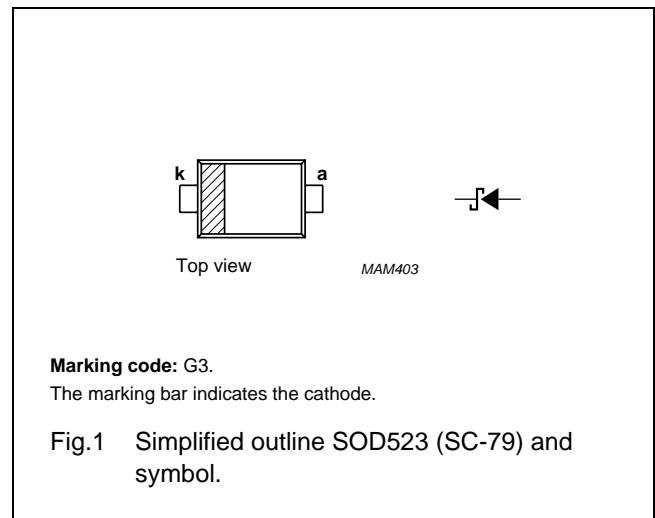
DESCRIPTION

Planar Schottky barrier diode in a SOD523 (SC-79) ultra small SMD plastic package.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	30	V
I_F	continuous forward current		–	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1 \text{ s}; \delta \leq 0.5$	–	300	mA
I_{FSM}	non-repetitive peak forward current	$t = 8.3 \text{ ms}$ half sine wave; JEDEC method	–	1 000	mA
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	125	°C
T_{amb}	operating ambient temperature		–65	+125	°C



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ELECTRICAL CHARACTERISTICS $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_F	forward voltage	see Fig.2;			
		$I_F = 0.1\text{ mA}$	130	190	mV
		$I_F = 1\text{ mA}$	190	250	mV
		$I_F = 10\text{ mA}$	255	300	mV
		$I_F = 100\text{ mA}$	355	410	mV
		$I_F = 200\text{ mA}$	420	500	mV
I_R	continuous reverse current	$V_R = 10\text{ V}$; note 1; see Fig.3	2.5	30	μA
C_d	diode capacitance	$V_R = 1\text{ V}$; $f = 1\text{ MHz}$; see Fig.4	20	25	pF

Note

1. Pulse test: $t_p = 300\text{ }\mu\text{s}$; $\delta = 0.02$.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	450	K/W

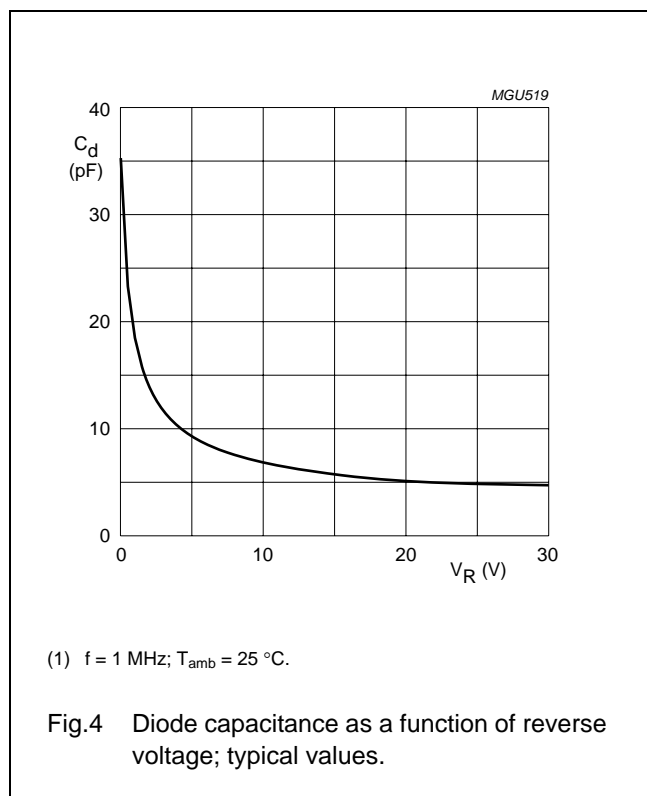
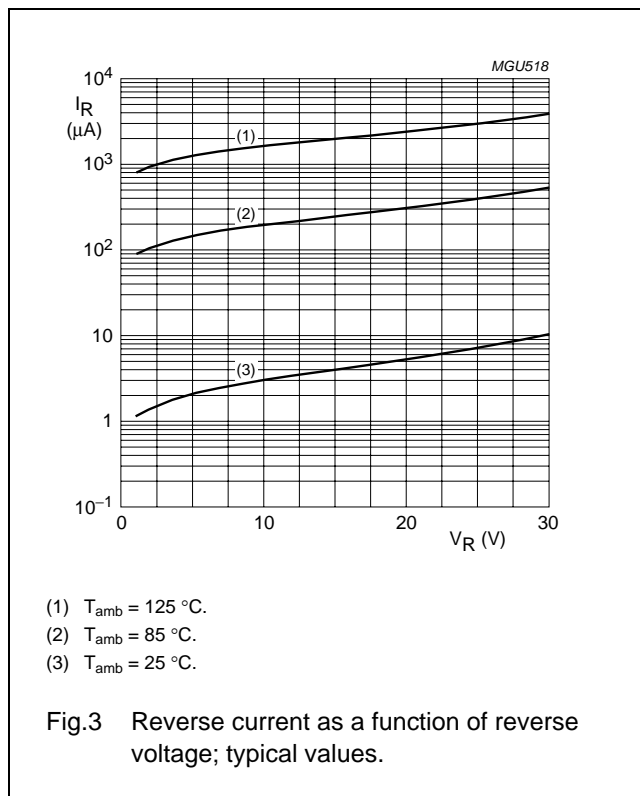
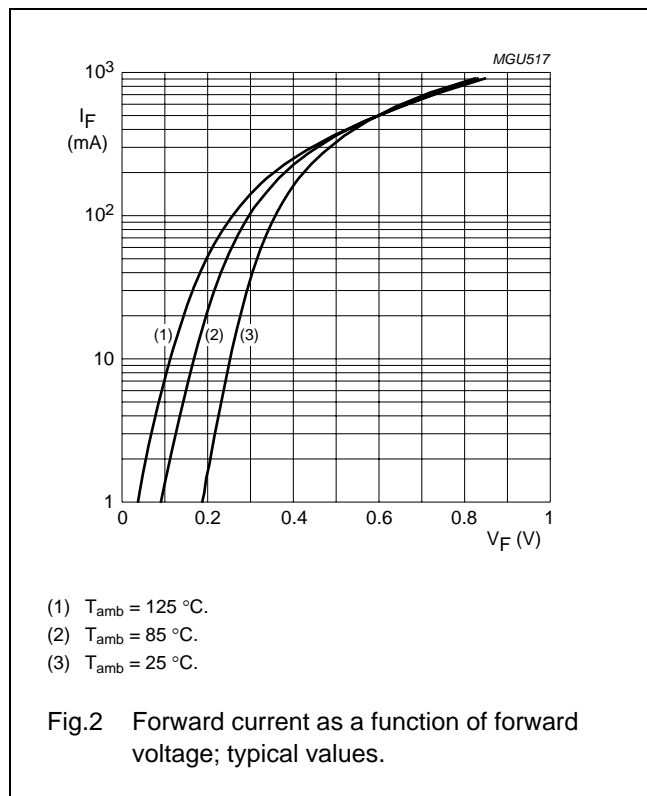
Note

1. Refer to SC-79 (SOD523) standard mounting conditions.

Schottky barrier diode

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GRAPHICAL DATA



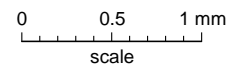
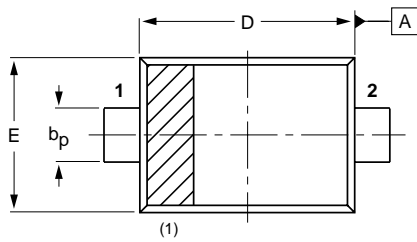
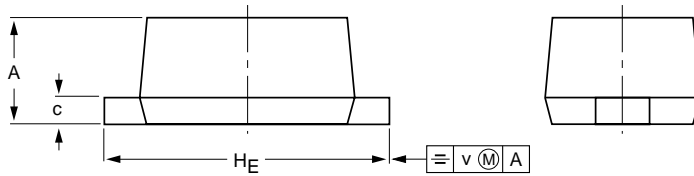
Schottky barrier diode

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PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD523




DIMENSIONS (mm are the original dimensions)

UNIT	A	b _p	c	D	E	H _E	v
mm	0.65	0.34	0.17	1.25	0.85	1.65	0.1
	0.58	0.26	0.11	1.15	0.75	1.55	

Note

1. The marking bar indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD523			SC-79			98-11-25- 02-12-13

Schottky barrier diode

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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